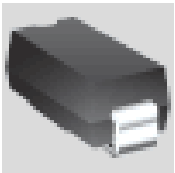


MATERIAL DECLARATION SHEET



Reliable Electronic Solutions

Material #	CD214B Series	
Product Line	Integrated Passive & Active Devices	
Date	8/2/2004	
RoHS Compliant	Yes	

COMPONENT DETAILS

No.	Construction element	Material group	Material weight [g]	Materials	CAS if applicable	Average mass [%]	Sum [%]	Traces
1	Dice	Silicon with metal	0.00465	Si	7440-21-3	4.9	5	Al, B, P, Pt, Cu,
				Ni	7440-02-0	.055		
2	High-melting point Solder paste	Tin-Lead solder	0.002325	Pb	7439-92-1	2.34	2.5	
				Sn	7440-31-5	.125		
				Ag	7440-22-4	.0375		
3	Lead frame & clip	Copper alloy	0.0399	Cu	7440-50-8	41.94	42.9	Zn,P
				Fe	7439-89-6	.9138		
4	Mold compound	Epoxy material	0.04557	Silica(SiO2)	7631-86-9	.34.3	49	
				Epoxy resin	68928-70-1	9.8		
				Sb2O3	1309-64-4	2.45		
				Phenolic resin	29690-82-2	2.54		
5	Plating cover	Tin solder	0.00093	Sn	7440-31-5	1	1	
			Total weight			0.09300		

Lead Part Number Example: CD214B-T6.0CA
 Pb Free Part Number Example: CD214B-T6.0CALF

Note: Avg. mass and sum data is a % of the component weight.
 It is the responsibility of the user to ensure that the latest revision is being accessed on the website.